



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
P0102DN 5AA4	EPLM*P0202M2	A	ZA41	2016-01-11
Amount	UoM	Unit type	ST ECOPACK Grade	
110.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.5 - 6.5 - 1.8	4	gull wing	
Comment	Package: SOT 223 PLANAR and TOPGLASS			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EPLM*P0202M2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.748	mg	supplier	die	Silicon (Si)	7440-21-3		0.705	mg	942513	6409
				supplier	metallization	Aluminum (Al)	7429-90-5		0.023	mg	30749	209
				supplier	Passivation	Silicon Oxide	7631-86-9		0.013	mg	17380	118
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1337	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.006	mg	8021	55
Leadframe	Copper & its alloys	52.427	mg	supplier	alloy	Copper(CU)	7440-50-8		51.722	mg	986553	470200
				supplier	alloy	Iron(Fe)	7439-89-6		0.052	mg	992	473
				supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.015	mg	286	136
				supplier	metallization	Silver(Ag)	7440-22-4		0.638	mg	12169	5800
				supplier	Soft solder	Silver(Ag)	7440-22-4		0.034	mg	25392	309
Soft solder	Other organic materials	1.339	mg	supplier	Soft solder	Tin(Sn)	7440-31-5		0.027	mg	20164	245
				JIG - R	Lead/Lead Compounds	Lead	7439-92-1	7a. Lead in high me	1.278	mg	954444	11618
Wire	Other organic materials	0.047	mg	supplier	Bonding wire	Copper(Cu)	7440-50-8		0.047	mg	1000000	427
Encapsulation	Other organic materials	54.510	mg	supplier	Molding compound	Silica Fused	60676-86-0		47.967	mg	879967	436064
				supplier	Molding compound	Epoxy,Cresol Novolac	29690-82-2		0.818	mg	15006	7436
				supplier	Molding compound	Phenol Resin	2.726	Proprietary	2.726	mg	50009	24782
				supplier	Molding compound	Epoxy Resin	2.726	Proprietary	2.726	mg	50009	24782
				supplier	Molding compound	Carbon Black	1333-86-4		0.273	mg	5008	2482
connections coating	Solder	0.929	mg	supplier	Connections coating	Tin(Sn)	7440-31-5		0.929	mg	1000000	8445